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8-BIT MICROCONTROLLER

GENERAL DESCRIPTION

The W78E516B is an 8-bit microcontroller which has an in-system programmable MTP-ROM for firmware updating. The instruction set of the W78E516B is fully compatible with the standard 8052. The W78E516B contains a 64K bytes of main MTP-ROM and a 4K bytes of auxiliary MTP-ROM which allows the contents of the 64KB main MTP-ROM to be updated by the loader program located at the 4KB auxiliary MTP-ROM; 512 bytes of on-chip RAM; four 8-bit bi-directional and bit-addressable I/O ports; an additional 4-bit port P4; three 16-bit timer/counters; a serial port. These peripherals are supported by a eight sources two-level interrupt capability. To facilitate programming and verification, the MTP-ROM inside the W78E516B allows the program memory to be programmed and read electronically. Once the code is confirmed, the user can protect the code for security.

The W78E516B microcontroller has two power reduction modes, idle mode and power-down mode, both of which are software selectable. The idle mode turns off the processor clock but allows for continued peripheral operation. The power-down mode stops the crystal oscillator for minimum power consumption. The external clock can be stopped at any time and in any state without affecting the processor.

FEATURES

- Fully static design 8-bit CMOS microcontroller up to 40 MHz.
- 64K bytes of in-system programmable MTP-ROM for Application Program (APROM).
- 4K bytes of auxiliary MTP-ROM for Loader Program (LDROM).
- 512 bytes of on-chip RAM. (including 256 bytes of AUX-RAM, software selectable)
- 64K bytes program memory address space and   64K bytes data memory address space.
- Four 8-bit bi-directional ports.
- One 4-bit multipurpose programmable port.
- Three 16-bit timer/counters
- One full duplex serial port
- Six-sources, two-level interrupt capability
- Built-in power management
- Code protection
- Packaged in
  - DIP   40: W78E516B-24/40
  - PLCC 44: W78E516BP-24/40

PIN CONFIGURATIONS

40-pin DIP (W78E516B)

T2, P1.0	1	40	VDD
T2EX, P1.1	2	39	P0.0, AD0
P1.2	3	38	P0.1, AD1
P1.3	4	37	P0.2, AD2
P1.4	5	36	P0.3, AD3
P1.5	6	35	P0.4, AD4
P1.6	7	34	P0.5, AD5
P1.7	8	33	P0.6, AD6
RST	9	32	P0.7, AD7
RXD, P3.0	10	31	$\overline{EA}$
TXD, P3.1	11	30	ALE
$\overline{INT0}$, P3.2	12	29	$\overline{PSEN}$
$\overline{INT1}$, P3.3	13	28	P2.7, A15
T0, P3.4	14	27	P2.6, A14
T1, P3.5	15	26	P2.5, A13
$\overline{WR}$, P3.6	16	25	P2.4, A12
$\overline{RD}$, P3.7	17	24	P2.3, A11
XTAL2	18	23	P2.2, A10
XTAL1	19	22	P2.1, A9
VSS	20	21	P2.0, A8

44-pin PLCC (W78E516BP)

P1.5	7	39 P0.4, AD4
P1.6	8	38 P0.5, AD5
P1.7	9	37 P0.6, AD6
RST	10	36 P0.7, AD7
RXD, P3.0	11	35 $\overline{EA}$
P4.3	12	34 P4.1
TXD, P3.1	13	33 ALE
$\overline{INT0}$, P3.2	14	32 $\overline{PSEN}$
$\overline{INT1}$, P3.3	15	31 P2.7, A15
T0, P3.4	16	30 P2.6, A14
T1, P3.5	17	29 P2.5, A13

Top pins: P1.4, P1.3, P1.2, P1.1/T2EX, P1.0/T2, P4.2, VDD, P0.0/AD0, P0.1/AD1, P0.2/AD2, P0.3/AD3
(6 5 4 3 2 1 44 43 42 41 40)

Bottom pins: P3.6/WR, P3.7/RD, XTAL2, XTAL1, VSS, P4.0, P2.0/A8, P2.1/A9, P2.2/A10, P2.3/A11, P2.4/A12
(18 19 20 21 22 23 24 25 26 27 28)

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PIN DESCRIPTION

SYMBOL	TYPE	DESCRIPTIONS
$\overline{EA}$	I	EXTERNAL ACCESS ENABLE: This pin forces the processor to execute the external ROM. The ROM address and data will not be presented on the bus if the $\overline{EA}$ pin is high.
$\overline{PSEN}$	O H	PROGRAM STORE ENABLE: $\overline{PSEN}$ enables the external ROM data in the Port 0 address/data bus. When internal ROM access is performed, no $\overline{PSEN}$ strobe signal outputs originate from this pin.
ALE	O H	ADDRESS LATCH ENABLE: ALE is used to enable the address latch that separates the address from the data on Port 0. ALE runs at 1/6th of the oscillator frequency.
RST	I L	RESET: A high on this pin for two machine cycles while the oscillator is running resets the device.
XTAL1	I	CRYSTAL 1: This is the crystal oscillator input. This pin may be driven by an external clock.
XTAL2	O	CRYSTAL 2: This is the crystal oscillator output. It is the inversion of XTAL1.
VSS	I	GROUND: ground potential.
VDD	I	POWER SUPPLY: Supply voltage for operation.
P0.0–P0.7	I/O D	PORT 0: Function is the same as that of standard 8052.
P1.0–P1.7	I/O H	PORT 1: Function is the same as that of standard 8052.
P2.0–P2.7	I/O H	PORT 2: Port 2 is a bi-directional I/O port with internal pull-ups. This port also provides the upper address bits for accesses to external memory.
P3.0–P3.7	I/O H	PORT 3: Function is the same as that of the standard 8052.
P4.0–P4.3	I/O H	PORT 4: A bi-directional I/O. See details below.

* Note: **TYPE** I: input, O: output, I/O: bi-directional, H: pull-high, L: pull-low, D: open drain

PORT4

Another bit-addressable port P4 is also available and only 4 bits (P4<3:0>) can be used. This port address is located at 0D8H with the same function as that of port P1,

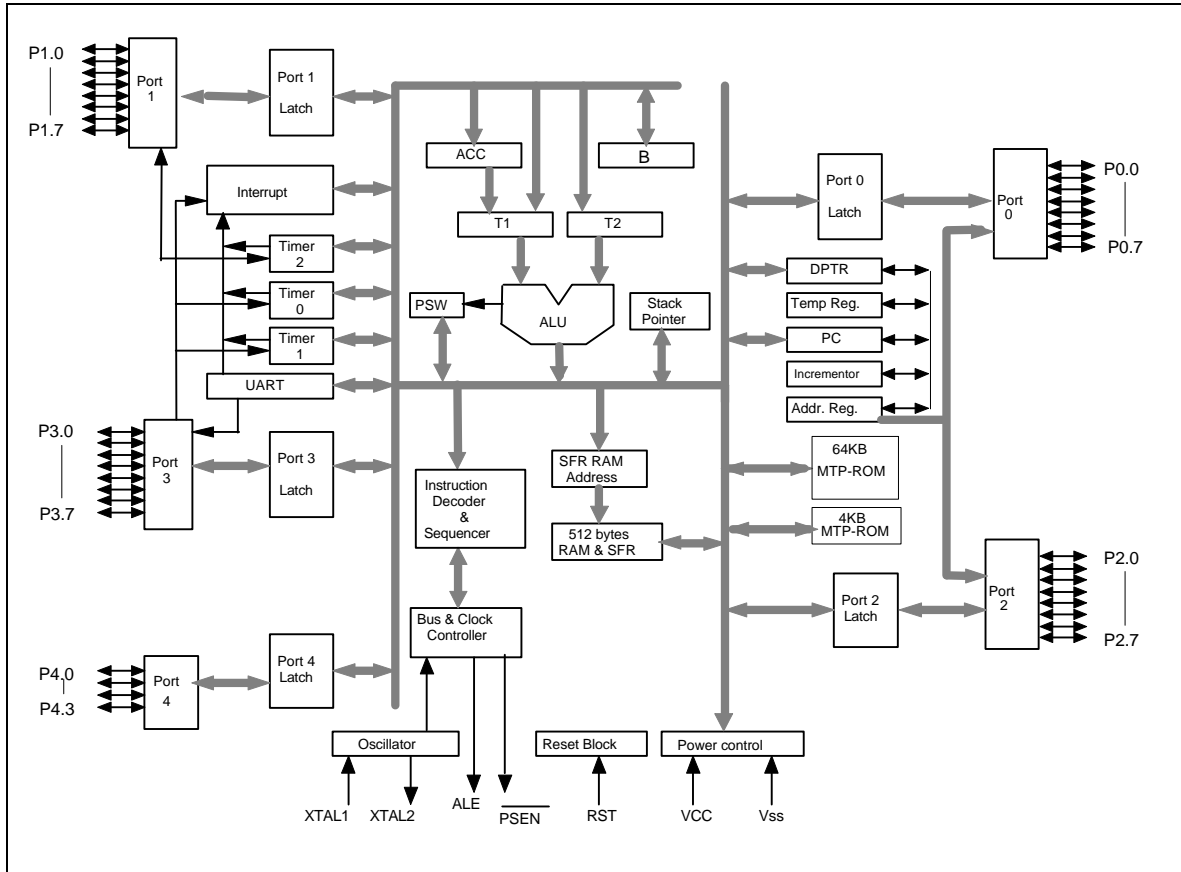Example:

```
P4      REG   0D8H

MOV     P4, #0AH    ; Output data "A" through P4.0–P4.3.

MOV     A, P4       ; Read P4 status to Accumulator.

SETB    P4.0        ; Set bit P4.0

CLR     P4.1        ; Clear bit P4.1
```

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BLOCK DIAGRAM

FUNCTIONAL DESCRIPTION

The W78E516B architecture consists of a core controller surrounded by various registers, four general purpose I/O ports, one special purpose programmable 4-bits I/O port, 512 bytes of RAM, three timer/counters, a serial port and an internal 74373 latch and 74244 buffer which can be switched to port2. The processor supports 111 different opcodes and references both a 64K program address space and a 64K data storage space.

RAM

The internal data RAM in the W78E516B is 512 bytes. It is divided into two banks: 256 bytes of scratchpad RAM and 256 bytes of AUX-RAM. These RAMs are addressed by different ways.

- RAM 0H−127H can be addressed directly and indirectly as the same as in 8051. Address pointers are R0 and R1 of the selected register bank.

- RAM 128H−255H can only be addressed indirectly as the same as in 8051. Address pointers are R0, R1 of the selected registers bank.

- AUX-RAM 0H–255H is addressed indirectly as the same way to access external data memory with the MOVX instruction. Address pointer are R0 and R1 of the selected register bank and DPTR register. An access to external data memory locations higher than 255H will be performed with the MOVX instruction in the same way as in the 8051. The AUX-RAM is disable after a reset. Setting the bit 4 in CHPCON register will enable the access to AUX-RAM. When AUX-RAM is enabled the instructions of "MOVX @Ri" will always access to on-chip AUX-RAM. When executing from internal program memory, an access to AUX-RAM will not affect the Ports P0, P2, $\overline{WR}$ and $\overline{RD}$.

Timers 0, 1, and 2

Timers 0, 1, and 2 each consist of two 8-bit data registers. These are called TL0 and TH0 for Timer 0, TL1 and TH1 for Timer 1, and TL2 and TH2 for Timer 2. The TCON and TMOD registers provide control functions for timers 0, 1. The T2CON register provides control functions for Timer 2. RCAP2H and RCAP2L are used as reload/capture registers for Timer 2. The operations of Timer 0 and Timer 1 are the same as in the W78C51. Timer 2 is a 16-bit timer/counter that is configured and controlled by the T2CON register. Like Timers 0 and 1, Timer 2 can operate as either an external event counter or as an internal timer, depending on the setting of bit C/T2 in T2CON. Timer 2 has three operating modes: capture, auto-reload, and baud rate generator. The clock speed at capture or auto-reload mode is the same as that of Timers 0 and 1.

Clock

The W78E516B is designed to be used with either a crystal oscillator or an external clock. Internally, the clock is divided by two before it is used by default. This makes the W78E516B relatively insensitive to duty cycle variations in the clock.

Crystal Oscillator

The W78E516B incorporates a built-in crystal oscillator. To make the oscillator work, a crystal must be connected across pins XTAL1 and XTAL2. In addition, a load capacitor must be connected from each pin to ground, and a resistor must also be connected from XTAL1 to XTAL2 to provide a DC bias when the crystal frequency is above 24 MHz.

External Clock

An external clock should be connected to pin XTAL1. Pin XTAL2 should be left unconnected. The XTAL1 input is a CMOS-type input, as required by the crystal oscillator. As a result, the external clock signal should have an input one level of greater than 3.5 volts.

Power Management

Idle Mode

The idle mode is entered by setting the IDL bit in the PCON register. In the idle mode, the internal clock to the processor is stopped. The peripherals and the interrupt logic continue to be clocked. The processor will exit idle mode when either an interrupt or a reset occurs.

Power-down Mode

When the PD bit in the PCON register is set, the processor enters the power-down mode. In this mode all of the clocks are stopped, including the oscillator. To exit from power-down mode is by a hardware reset or external interrupts $\overline{INT0}$ to $\overline{INT1}$ when enabled and set to level triggered.

Reduce EMI Emission

The W78E516B allows user to diminish the gain of on-chip oscillator amplifier by using programmer

to clear the B7 bit of security register. Once B7 is set to 0, a half of gain will be decreased. Care must be taken if user attempts to diminish the gain of oscillator amplifier, reducing a half of gain may affect the external crystal operating improperly at high frequency above 24 MHz. The value of R and C1, C2 may need some adjustment while running at lower gain.

Reset

The external RESET signal is sampled at S5P2. To take effect, it must be held high for at least two machine cycles while the oscillator is running. An internal trigger circuit in the reset line is used to deglitch the reset line when the W78E516B is used with an external RC network. The reset logic also has a special glitch removal circuit that ignores glitches on the reset line. During reset, the ports are initialized to FFH, the stack pointer to 07H, PCON (with the exception of bit 4) to 00H, and all of the other SFR registers except SBUF to 00H. SBUF is not reset.

W78E516B Special Function Registers (SFRs) and Reset Values

F8								FF
F0	+B 00000000					CHPENR 00000000		F7
E8								EF
E0	+ACC 00000000							E7
D8	**+P4 xxxx1111**							DF
D0	+PSW 00000000							D7
C8	+T2CON 00000000		RCAP2L 00000000	RCAP2H 00000000	TL2 00000000	TH2 00000000			CF
C0	XICON 00000000			**SFRAL 00000000**	**SFRAH 00000000**	**SFRFD 00000000**	**SFRCN 00000000**	C7
B8	+IP 00000000						**CHPCON 0xx00000**	BF
B0	+P3 00000000							B7
A8	+IE 00000000							AF
A0	+P2 11111111							A7
98	+SCON 00000000	SBUF xxxxxxxx						9F
90	+P1 11111111							97
88	+TCON 00000000	TMOD 00000000	TL0 00000000	TL1 00000000	TH0 00000000	TH1 00000000			8F
80	+P0 11111111	SP 00000111	DPL 00000000	DPH 00000000			PCON 00110000	87

Notes:

1.The SFRs marked with a plus sign(+) are both byte- and bit-addressable.

2. The text of SFR with bold type characters are extension function registers.

Port 4 (D8H)

BIT	NAME	FUNCTION
7	-	Reserve
6	-	Reserve
5	-	Reserve
4	-	Reserve
3	P43	Port 4 Data bit which outputs to pin P4.3.
2	P42	Port 4 Data bit. which outputs to pin P4.2.
1	P41	Port 4 Data bit. which outputs to pin P4.1.
0	P40	Port 4 Data bit which outputs to pin P4.0.

In-System Programming (ISP) Mode

The W78E516B equips one 64K byte of main MTP-ROM bank for application program (called APROM) and one 4K byte of auxiliary MTP-ROM bank for loader program (called LDROM). In the normal operation, the microcontroller executes the code in the APROM. If the content of APROM needs to be modified, the W78E516B allows user to activate the In-System Programming (ISP) mode by setting the CHPCON register. **The CHPCON is read-only by default, software must write two specific values 87H, then 59H sequentially to the CHPENR register to enable the CHPCON write attribute. Writing CHPENR register with the values except 87H and 59H will close CHPCON register write attribute.** The W78E516B achieves all in-system programming operations including enter/exit ISP Mode, program, erase, read ... etc, during device in the idle mode. Setting the bit CHPCON.0 the device will enter in-system programming mode after a wake-up from idle mode. Because device needs proper time to complete the ISP operations before awaken from idle mode, software may use timer interrupt to control the duration for device wake-up from idle mode. To perform ISP operation for revising contents of APROM, software located at APROM setting the CHPCON register then enter idle mode, after awaken from idle mode the device executes the corresponding interrupt service routine in LDROM. Because the device will clear the program counter while switching from APROM to LDROM, the first execution of RETI instruction in interrupt service routine will jump to 00H at LDROM area. The device offers a software reset for switching back to APROM while the content of APROM has been updated completely. **Setting CHPCON register bit 0, 1 and 7 to logic-1 will result a software reset to reset the CPU**. The software reset serves as a external reset. This in-system programming feature makes the job easy and efficient in which the application needs to update firmware frequently. In some applications, the in-system programming feature make it possible to easily update the system firmware without opening the chassis.

SFRAH, SFRAL: The objective address of on-chip MTP-ROM in the in-system programming mode. SFRFAH contains the high-order byte of address, SFRFAL contains the low-order byte of address.

SFRFD: The programming data for on-chip MTP-ROM in programming mode.

SFRCN: The control byte of on-chip MTP-ROM programming mode.

SFRCN (C7)

BIT	NAME	FUNCTION
7	-	Reserve.
6	WFWIN	On-chip MTP-ROM bank select for in-system programming. = 0: 64K bytes MTP-ROM bank is selected as destination for re-programming. = 1: 4K bytes MTP-ROM bank is selected as destination for re-programming.
5	OEN	MTP-ROM output enable.
4	CEN	MTP-ROM chip enable.
3, 2, 1, 0	CTRL[3:0]	The flash control signals

MODE	WFWIN	CTRL<3:0>	OEN	CEN	SFRAH, SFRAL	SFRFD
Erase 64KB APROM	0	0010	1	0	X	X
Program 64KB APROM	0	0001	1	0	Address in	Data in
Read 64KB APROM	0	0000	0	0	Address in	Data out
Erase 4KB LDROM	1	0010	1	0	X	X
Program 4KB LDROM	1	0001	1	0	Address in	Data in
Read 4KB LDROM	1	0000	0	0	Address in	Data out

In-System Programming Control Register (CHPCON)

CHPCON (BFH)

BIT	NAME	FUNCTION
7	SWRESET (F04KMODE)	When this bit is set to 1, and both FBOOTSL and FPROGEN are set to 1. It will enforce microcontroller reset to initial condition just like power on reset. This action will re-boot the microcontroller and start to normal operation. To read this bit in logic-1 can determine that the F04KBOOT mode is running.
6	-	Reserve.
5	-	Reserve.
4	ENAUXRAM	1: Enable on-chip AUX-RAM. 0: Disable the on-chip AUX-RAM
3	0	Must set to 0.
2	0	Must set to 0.
1	FBOOTSL	The Program Location Select. 0: The Loader Program locates at the 64 KB APROM. 4KB LDROM is destination for re-programming. 1: The Loader Program locates at the 4 KB memory bank. 64KB APROM is destination for re-programming.

CHPCON (BFH), continued

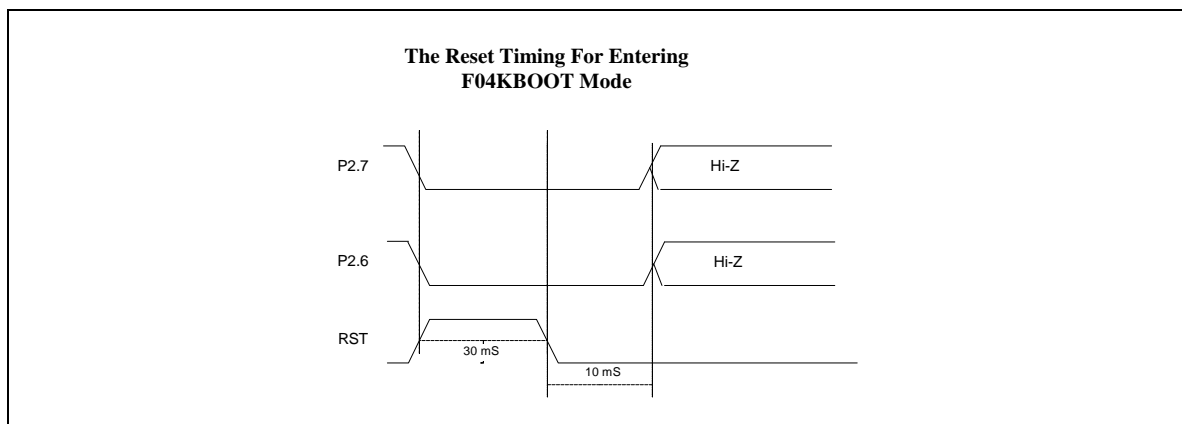| BIT	NAME	FUNCTION
0	FPROGEN	-ROM Programming Enable. = 1: enable. The microcontroller enter the in- mode after -up from interrupt. During in system programming mode, the operation of erase, program and read are acheived when device enters idle mode. -chip flash memory is read only. In-

F04KBOOT Mode (Boot From LDROM)

By default, the W78E516B boots from APROM program after a power on reset. On some occasions, user can force the W78E516B to boot from the LDROM program via following setting
situation that you need to enter F04KBOOT mode is when the APROM program can not run properly and device can not jump back to LDROM to execute in system programming function. Then you can use this F04KBOOT mode to force the W78E516B jumps t   -system

switches or jumpers. For example in a CD-
and EJECT buttons on the panel. When the APROM program fails to execute the normal application

personal computer to force the W78E516B to enter the F04KBOOT mode. After power on of personal computer, you   -system programming procedure to update the APROM code. In application system design, user must take care of the P2, P3, ALE, $\overline{EA}$ and $\overline{PSEN}$ pin value at reset to prevent from accidentally activating the programming mode or F04KBOOT mode.

F04KBOOT MODE

P4.3	P2.7	P2.6	MODE
X	L	L	FO4KBOOT
L	X	X	FO4KBOOT

**The Reset Timing For Entering
F04KBOOT Mode**

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The Algorithm of In-System Programming

Part 1:64KB APROM
procedure of entering
In-System Programming Mode

START

Enter In-System
Programming Mode ?
(conditions depend on
user's application)

No

Yes

Setting control registers
MOV CHPENR,#87H
MOV CHPENR,#59H
MOV CHPCON,#03H

Execute the normal application
program

Setting Timer (about 1.5 us)
and enable timer interrupt

END

Start Timer and enter idle Mode.

(CPU will be wakened from idle mode
by timer interrupt, then enter In-System
Programming mode)

CPU will be wakened by interrupt and
re-boot from 4KB LDROM to execute
the loader program.

Go

Go

Timer Interrupt Service Routine:
Stop Timer & disable interrupt

Is F04KBOOT Mode?
(CHPCON.7=1)

Yes → Reset the CHPCON Register:

MOV CHPENR,#87H
MOV CHPENR,#59H
MOV CHPCON,#03H

No

Setting Timer and enable Timer
interrupt for wake-up .
(15 ms for erasing operation)

Setting erase operation mode:
MOV SFRCN,#22H
(Erase 64KB APROM)

Start Timer and enter IDLE
Mode.
(Erasing...)

End of erase
operation. CPU will
be wakened by Timer
interrupt.

PGM

Part 2: 4KB LDROM

Procedure of Updating
the 64KB APROM

PGM

End of Programming ?

Yes

No

Setting Timer and enable Timer
interrupt for wake-up .
(150us for program operation)

Get the parameters of new code
(Address and data bytes)
through I/O ports, UART or
other interfaces.

Setting control registers for
programming:

MOV SFRAH,#ADDRESS_H
MOV SFRAL,#ADDRESS_L
MOV SFRFD,#DATA
MOV SFRCN,#21H

Is currently in the
F04KBOOT Mode ?

Yes

No

Software reset CPU and
re-boot from the 64KB
APROM.
MOV CHPENR,#87H
MOV CHPENR,#59H
MOV CHPCON,#83H

Hardware Reset
to re-boot from
new 64 KB APROM.
**(S/W reset is
invalid in F04KBOOT
Mode)**

END
Executing new code
from address
00H in the 64KB APROM.

SECURITY

During the on-chip MTP-ROM programming mode, the MTP-ROM can be programmed and verified repeatedly. Until the code inside the MTP-ROM is confirmed OK, the code can be protected. The protection of MTP-ROM and those operations on it are described below.

The W78E516B has several Special Setting Registers, including the Security Register and Company/Device ID Registers, which can not be accessed in programming mode. Those bits of the Security Registers can not be changed once they have been programmed from high to low. They can only be reset through erase-all operation. The contents of the Company ID and Device ID registers have been set in factory. The Security Register is located at the 0FFFFH of the LDROM space.

Special Setting Registers
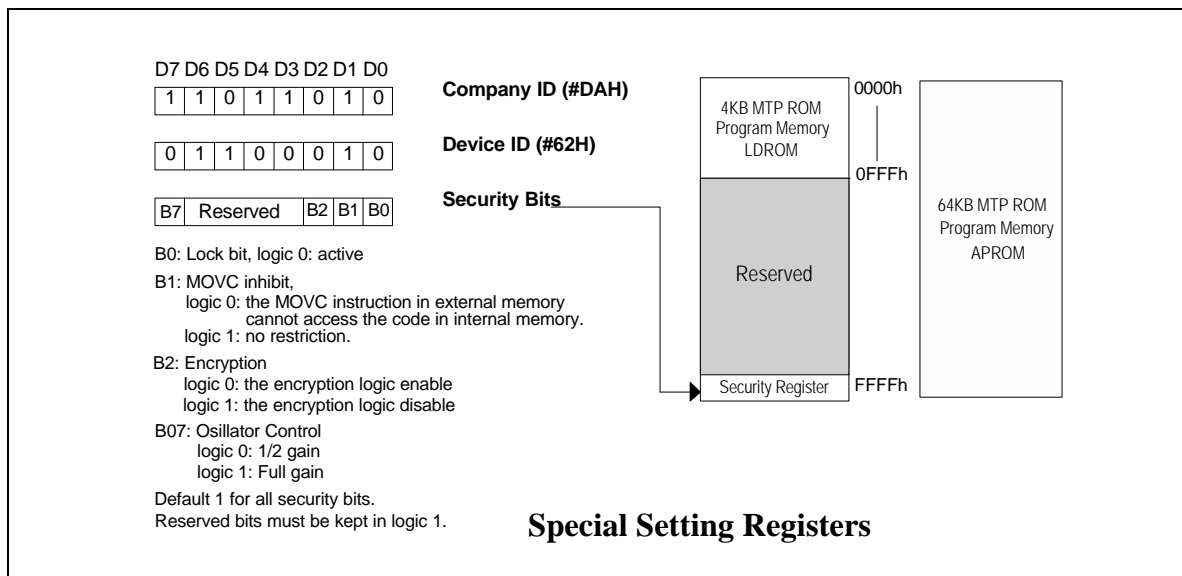
Lock bit

This bit is used to protect the customer's program code in the W78E516B. It may be set after the programmer finishes the programming and verifies sequence. Once this bit is set to logic 0, both the MTP ROM data and Special Setting Registers can not be accessed again.

MOVC Inhibit

This bit is used to restrict the accessible region of the MOVC instruction. It can prevent the MOVC instruction in external program memory from reading the internal program code. When this bit is set to logic 0, a MOVC instruction in external program memory space will be able to access code only in the external memory, not in the internal memory. A MOVC instruction in internal program memory space will always be able to access the ROM data in both internal and external memory. If this bit is logic 1, there are no restrictions on the MOVC instruction.

Encryption

This bit is used to enable/disable the encryption logic for code protection. Once encryption feature is enabled, the data presented on port 0 will be encoded via encryption logic. Only whole chip erase will reset this bit.

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Oscillator Control

W78E516B/E516 allow user to diminish the gain of on-chip oscillator amplifier by using programmer to set the bit B7 of security register. Once B7 is set to 0, a half of gain will be decreased. Care must be taken if user attempts to diminish the gain of oscillator amplifier, reducing a half of gain may improperly affect the external crystal operation at high frequency above 24 MHz. The value of R and C1, C2 may need some adjustment while running at lower gain.

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	MIN.	MAX.	UNIT
DC Power Supply	V_{DD}–V_{SS}	-0.3	+6.0	V
Input Voltage	V_{IN}	V_{SS} -0.3	V_{DD} +0.3	V
Operating Temperature	T_A	0	70	°C
Storage Temperature	T_{ST}	-55	+150	°C

Note: Exposure to conditions beyond those listed under Absolute Maximum Ratings may adversely affect the life and reliability of the device.

D.C. ELECTRICAL CHARACTERISTICS

(V_{DD}-V_{SS} = 5V ±10%, T_A = 25°C, F_{osc} = 20 MHz, unless otherwise specified.)

PARAMETER	SYM.	SPECIFICATION			TEST CONDITIONS
		MIN.	MAX.	UNIT	
Operating Voltage	V_{DD}	4.5	5.5	V	RST = 1, P0 = V_{DD}
Operating Current	I_{DD}	-	20	mA	No load V_{DD} = 5.5V
Idle Current	I_{IDLE}	-	6	mA	Idle mode V_{DD} = 5.5V
Power Down Current	I_{PWDN}	-	50	μA	Power-down mode V_{DD} = 5.5V
Input Current P1, P2, P3, P4	I_{IN1}	-50	+10	μA	V_{DD} = 5.5V V_{IN} = 0V or V_{DD}
Input Current RST	I_{IN2}	-10	+300	μA	V_{DD} = 5.5V 0< V_{IN} <V_{DD}
Input Leakage Current P0, $\overline{EA}$	I_{LK}	-10	+10	μA	V_{DD} = 5.5V 0V< V_{IN} < V_{DD}
Logic 1 to 0 Transition Current P1, P2, P3, P4	I_{TL}[*4]	-500	-	μA	V_{DD} = 5.5V V_{IN} = 2.0V
Input Low Voltage P0, P1, P2, P3, P4, $\overline{EA}$	V_{IL1}	0	0.8	V	V_{DD} = 4.5V

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D.C. Electrical Characteristics, continued

PARAMETER	SYM.	SPECIFICATION			TEST CONDITIONS
		MIN.	MAX.	UNIT	
Input Low Voltage RST	V$_{IL2}$	0	0.8	V	V$_{DD}$ = 4.5V
Input Low Voltage XTAL1[*4]	V$_{IL3}$	0	0.8	V	V$_{DD}$ = 4.5V
Input High Voltage P0, P1, P2, P3, P4, $\overline{EA}$	V$_{IH1}$	2.4	V$_{DD}$ +0.2	V	V$_{DD}$ = 5.5V
Input High Voltage RST	V$_{IH2}$	3.5	V$_{DD}$ +0.2	V	V$_{DD}$ = 5.5V
Input High Voltage XTAL1[*4]	V$_{IH3}$	3.5	V$_{DD}$ +0.2	V	V$_{DD}$ = 5.5V
Output Low Voltage P1, P2, P3, P4	V$_{OL1}$	-	0.45	V	V$_{DD}$ = 4.5V I$_{OL}$ = +2 mA
Output Low Voltage P0, ALE, $\overline{PSEN}$ [*3]	V$_{OL2}$	-	0.45	V	V$_{DD}$ = 4.5V I$_{OL}$ = +4 mA
Sink Current P1, P3, P4	Isk1	4	12	mA	V$_{DD}$ = 4.5V V$_{IN}$ = 0.45V
Sink Current P0, P2, ALE, $\overline{PSEN}$	Isk2	10	20	mA	V$_{DD}$ = 4.5V V$_{IN}$ = 0.45V
Output High Voltage P1, P2, P3, P4	V$_{OH1}$	2.4	-	V	V$_{DD}$ = 4.5V I$_{OH}$ = -100 μA
Output High Voltage P0, ALE, $\overline{PSEN}$ [*3]	V$_{OH2}$	2.4	-	V	V$_{DD}$ = 4.5V I$_{OH}$ = -400 μA
Source Current P1, P2, P3, P4	Isr1	-120	-250	μA	V$_{DD}$ = 4.5V V$_{IN}$ = 2.4V
Source Current P0, P2, ALE, $\overline{PSEN}$	Isr2	-8	-20	mA	V$_{DD}$ = 4.5V V$_{IN}$ = 2.4V

Notes:

*1. RST pin is a Schmitt trigger input.

*3. P0, ALE and $\overline{PSEN}$ are tested in the external access mode.

*4. XTAL1 is a CMOS input.

*5. Pins of P1, P2, P3 , P4 can source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V$_{IN}$ approximates to 2V.

AC CHARACTERISTICS

The AC specifications are a function of the particular process used to manufacture the part, the ratings of the I/O buffers, the capacitive load, and the internal routing capacitance. Most of the specifications can be expressed in terms of multiple input clock periods (T_{CP}), and actual parts will usually experience less than a ±20 nS variation. The numbers below represent the performance expected from a 0.6 micron CMOS process when using 2 and 4 mA output buffers.

Clock Input Waveform
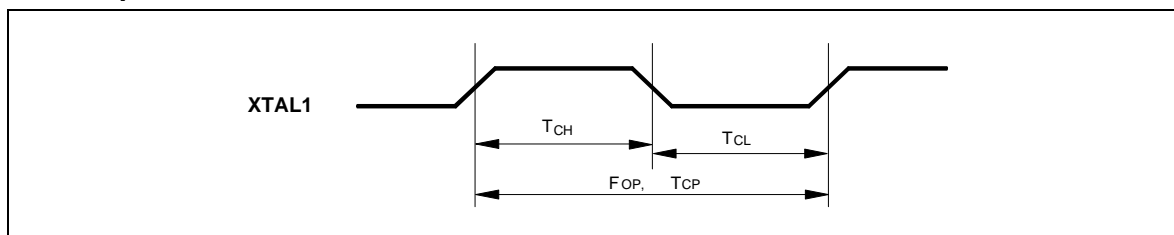
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTES
Operating Speed	Fop	0	-	40	MHz	1
Clock Period	TCP	25	-	-	nS	2
Clock High	Tch	10	-	-	nS	3
Clock Low	Tcl	10	-	-	nS	3

Notes:

1. The clock may be stopped indefinitely in either state.

2. The T_{CP} specification is used as a reference in other specifications.

3. There are no duty cycle requirements on the XTAL1 input.

Program Fetch Cycle

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTES
Address Valid to ALE Low	TAAS	1 TCP-Δ	-	-	nS	4
Address Hold from ALE Low	TAAH	1 TCP-Δ	-	-	nS	1, 4
ALE Low to $\overline{PSEN}$ Low	TAPL	1 TCP-Δ	-	-	nS	4
$\overline{PSEN}$ Low to Data Valid	TPDA	-	-	2 TCP	nS	2
Data Hold after $\overline{PSEN}$ High	TPDH	0	-	1 TCP	nS	3
Data Float after $\overline{PSEN}$ High	TPDZ	0	-	1 TCP	nS	
ALE Pulse Width	TALW	2 TCP-Δ	2 TCP	-	nS	4
$\overline{PSEN}$ Pulse Width	TPSW	3 TCP-Δ	3 TCP	-	nS	4

Notes:

1. P0.0–P0.7, P2.0–P2.7 remain stable throughout entire memory cycle.

2. Memory access time is 3 T_{CP}.

3. Data have been latched internally prior to $\overline{PSEN}$ going high.

4. "Δ" (due to buffer driving delay and wire loading) is 20 nS.

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Data Read Cycle

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTES
ALE Low to $\overline{RD}$ Low	TDAR	3 TCP-Δ	-	3 TCP+Δ	nS	1, 2
$\overline{RD}$ Low to Data Valid	TDDA	-	-	4 TCP	nS	1
Data Hold from $\overline{RD}$ High	TDDH	0	-	2 TCP	nS	
Data Float from $\overline{RD}$ High	TDDZ	0	-	2 TCP	nS	
$\overline{RD}$ Pulse Width	TDRD	6 TCP-Δ	6 TCP	-	nS	2

Notes:
1. Data memory access time is 8 TCP.
2. "Δ" (due to buffer driving delay and wire loading) is 20 nS.

Data Write Cycle

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
ALE Low to $\overline{WR}$ Low	TDAW	3 TCP-Δ	-	3 TCP+Δ	nS
Data Valid to $\overline{WR}$ Low	TDAD	1 TCP-Δ	-	-	nS
Data Hold from $\overline{WR}$ High	TDWD	1 TCP-Δ	-	-	nS
$\overline{WR}$ Pulse Width	TDWR	6 TCP-Δ	6 TCP	-	nS

Note: "Δ" (due to buffer driving delay and wire loading) is 20 nS.

Port Access Cycle

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Port Input Setup to ALE Low	TPDS	1 TCP	-	-	nS
Port Input Hold from ALE Low	TPDH	0	-	-	nS
Port Output to ALE	TPDA	1 TCP	-	-	nS

Note: Ports are read during S5P2, and output data becomes available at the end of S6P2. The timing data are referenced to ALE, since it provides a convenient reference.

TIMING WAVEFORMS

Program Fetch Cycle
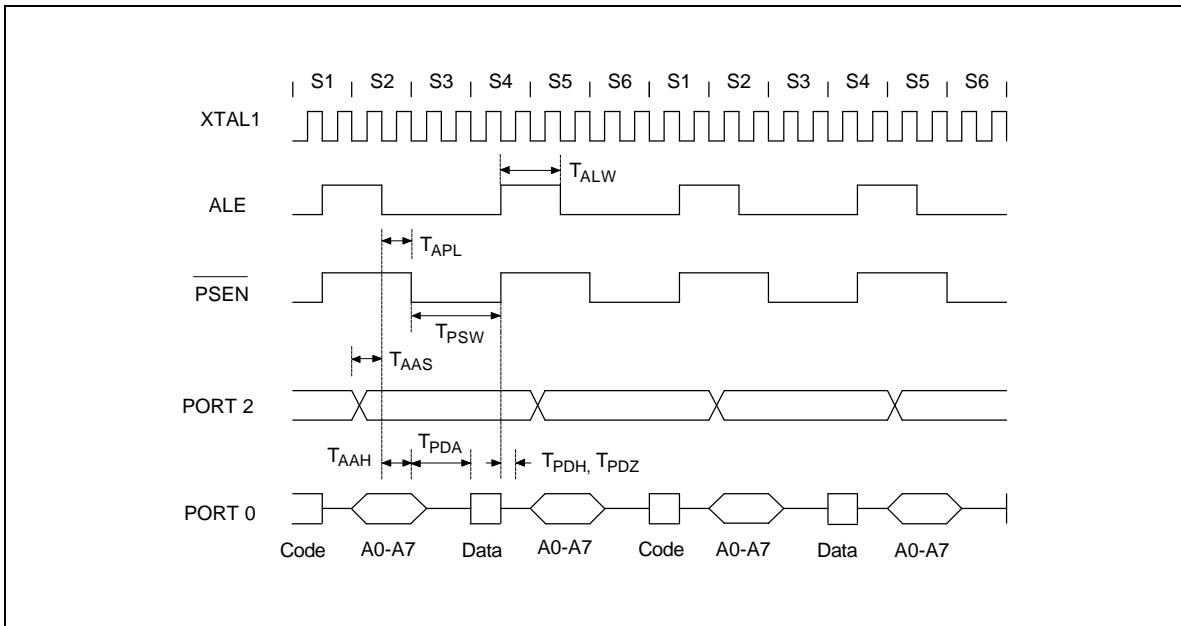
Data Read Cycle
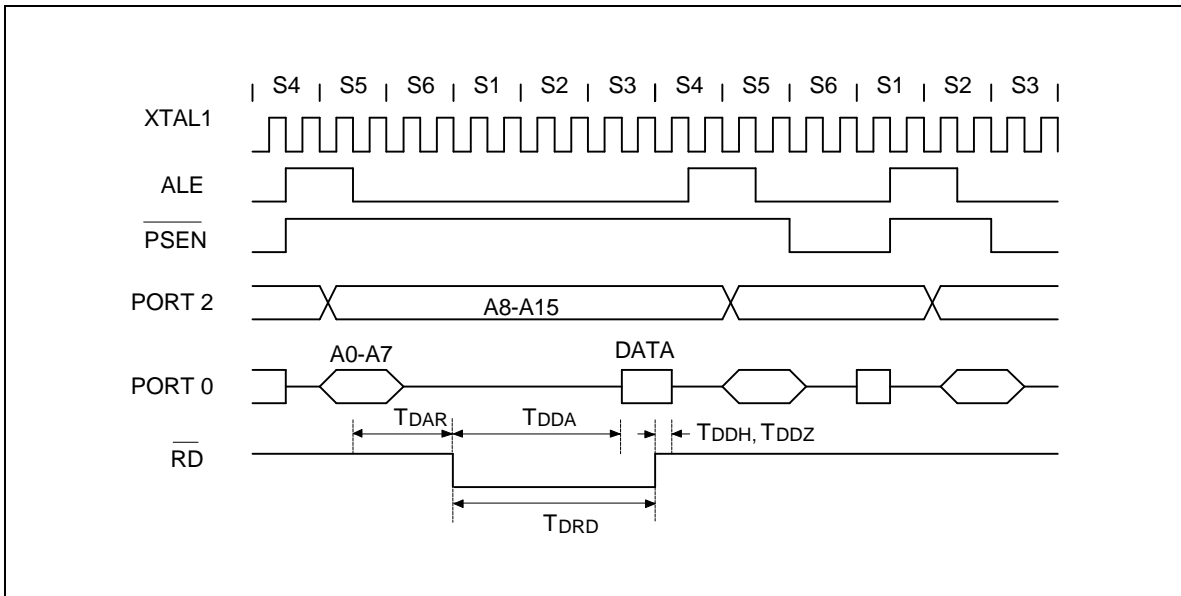
Timing Waveforms, continued

Data Write Cycle

Port Access Cycle

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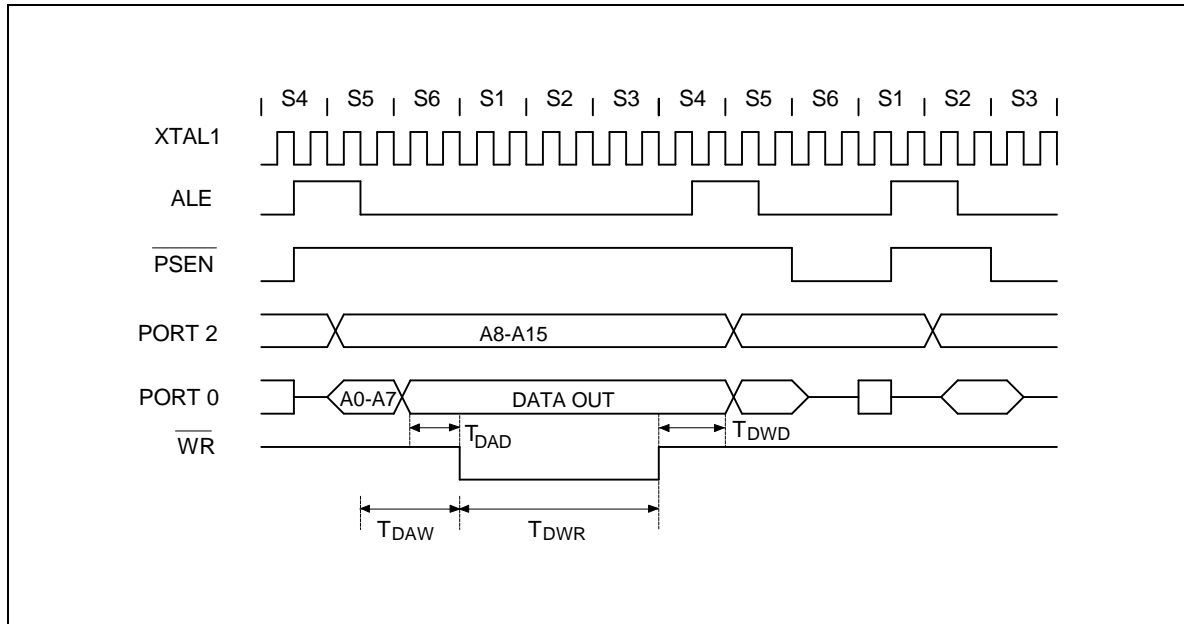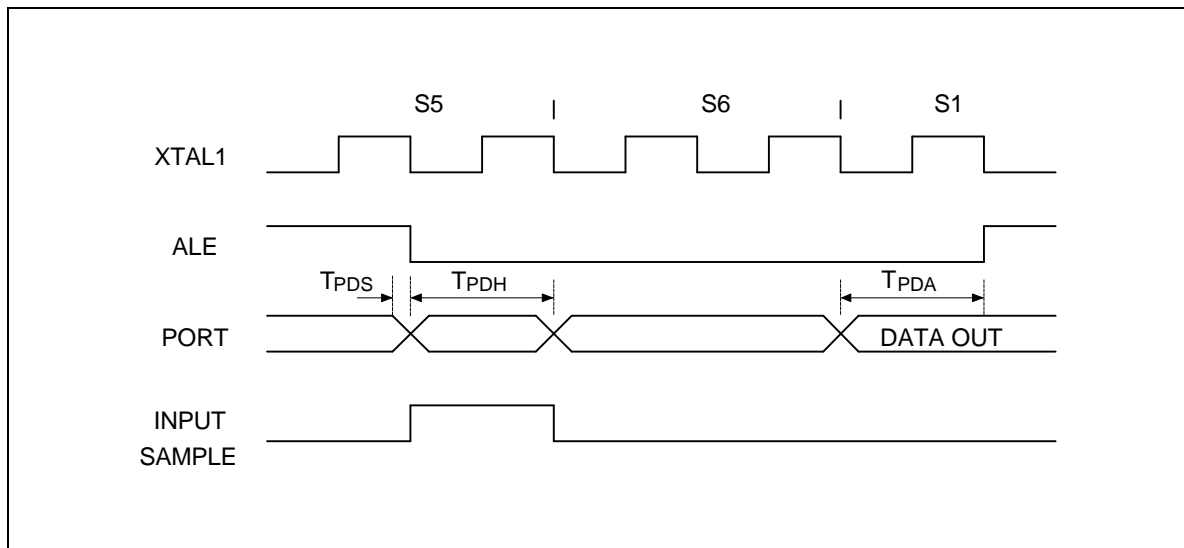
TYPICAL APPLICATION CIRCUIT

Expanded External Program Memory and Crystal
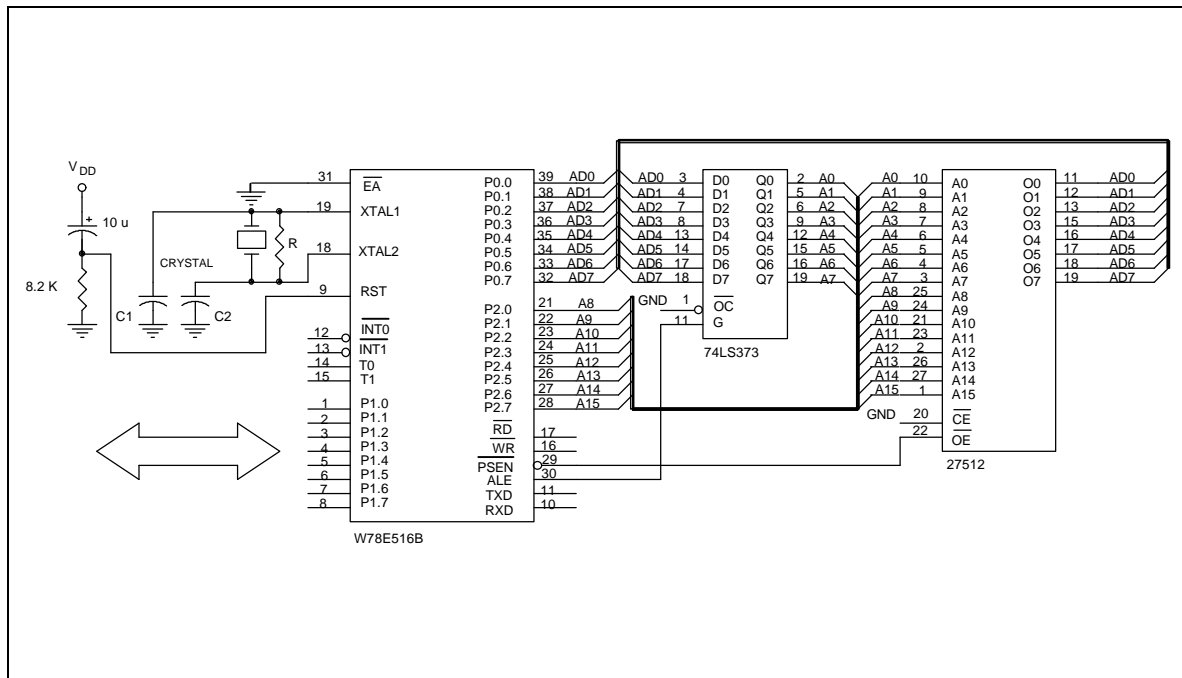
Figure A

CRYSTAL	C1	C2	R
6 MHz	47P	47P	-
16 MHz	30P	30P	-
24 MHz	15P	10P	-
32 MHz	10P	10P	6.8K
40 MHz	5P	5P	4.7K

Above table shows the reference values for crystal applications.

Notes:

1. C1, C2, R components refer to Figure A

2. Crystal layout must get close to XTAL1 and XTAL2 pins on user's application board.

Tipical Application Circuit, continued

Expanded External Data Memory and Oscillator

Figure B

PACKAGE DIMENSIONS

40-pin DIP

Symbol	Dimension in inch			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	—	—	0.210	—	—	5.334
A1	0.010	—	—	0.254	—	—
A2	0.150	0.155	0.160	3.81	3.937	4.064
B	0.016	0.018	0.022	0.406	0.457	0.559
B1	0.048	0.050	0.054	1.219	1.27	1.372
c	0.008	0.010	0.014	0.203	0.254	0.356
D	—	2.055	2.070	—	52.20	52.58
E	0.590	0.600	0.610	14.986	15.24	15.494
E1	0.540	0.545	0.550	13.72	13.84	13.97
e1	0.090	0.100	0.110	2.286	2.54	2.794
L	0.120	0.130	0.140	3.048	3.302	3.556
a	0	—	15	0	—	15
eA	0.630	0.650	0.670	16.00	16.51	17.01
S	—	—	0.090	—	—	2.286

Notes:
1. Dimension D Max. & S include mold flash or tie bar burrs.
2. Dimension E1 does not include interlead flash.
3. Dimension D & E1 include mold mismatch and are determined at the mold parting line.
4. Dimension B1 does not include dambar protrusion/intrusion.
5. Controlling dimension: Inches.
6. General appearance spec. should be based on final visual inspection spec.

44-pin PLCC

Symbol	Dimension in inch			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	—	—	0.185	—	—	4.699
A1	0.020	—	—	0.508	—	—
A2	0.145	0.150	0.155	3.683	3.81	3.937
b1	0.026	0.028	0.032	0.66	0.711	0.813
b	0.016	0.018	0.022	0.406	0.457	0.559
c	0.008	0.010	0.014	0.203	0.254	0.356
D	0.648	0.653	0.658	16.46	16.59	16.71
E	0.648	0.653	0.658	16.46	16.59	16.71
e	0.050 BSC			1.27 BSC		
GD	0.590	0.610	0.630	14.99	15.49	16.00
GE	0.590	0.610	0.630	14.99	15.49	16.00
HD	0.680	0.690	0.700	17.27	17.53	17.78
HE	0.680	0.690	0.700	17.27	17.53	17.78
L	0.090	0.100	0.110	2.296	2.54	2.794
y	—	—	0.004	—	—	0.10

Notes:
1. Dimension D & E do not include interlead flash.
2. Dimension b1 does not include dambar protrusion/intrusion.
3. Controlling dimension: Inches
4. General appearance spec. should be based on final visual inspection spec.
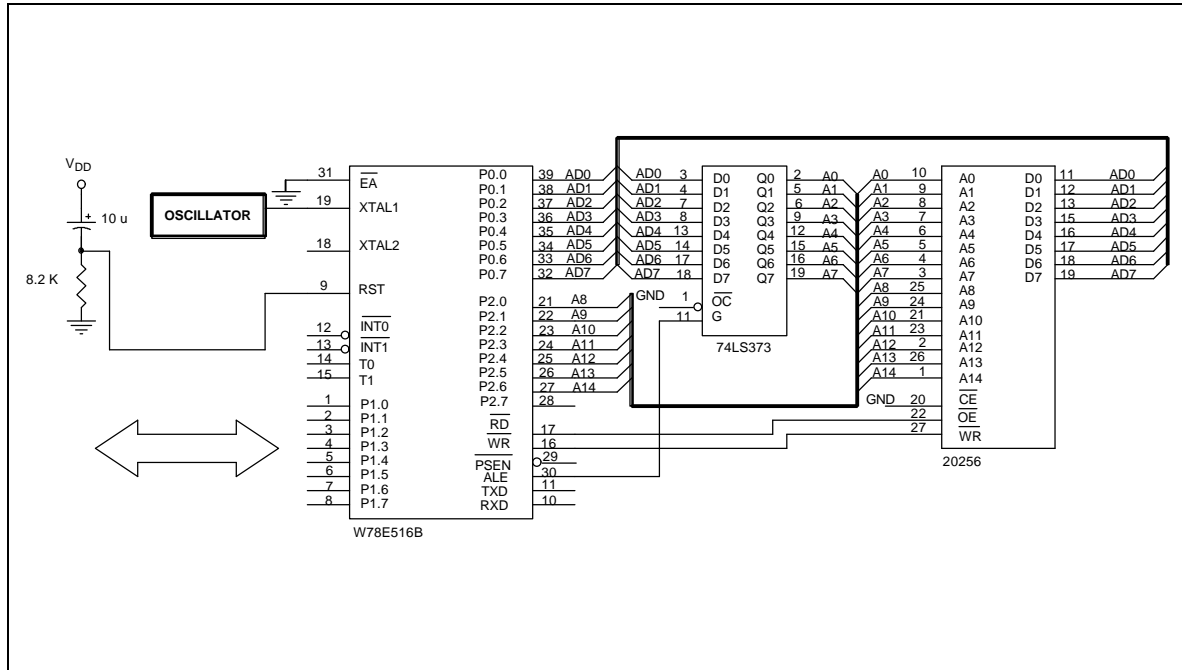
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Application Note: In-system Programming Software Examples

This application note illustrates the in-system programmability of the Winbond W78E516B MTP-ROM microcontroller. In this example, microcontroller will boot from 64KB APROM bank and waiting for a key to enter in-system programming mode for re-programming the contents of 64KB APROM. While entering in-system programming mode, microcontroller excutes the loader program in 4KB LDROM bank. The loader program erases the 64KB APROM then reads the new code data from external SRAM buffer (or through other interfaces) to update the 64KB APROM.

EXAMPLE 1:

```
;******************************************************************************************************
;* Example of 64K APROM program: Program will scan the P1.0. if P1.0 = 0, enters in-system
;* programming mode for updating thecontents of APROM code else excutes the current ROM code.
;* XTAL = 40 MHz
;******************************************************************************************************
;
    .chip 8052
    .RAMCHK OFF
    .symbols

    CHPCON   EQU    BFH
    CHPENR   EQU    F6H
    SFRAL    EQU    C4H
    SFRAH    EQU    C5H
    SFRFD    EQU    C6H
    SFRCN    EQU    C7H


    ORG    0H
    LJMP   100H           ; JUMP TO MAIN PROGRAM
;************************************************************************
;
;*  TIMER0 SERVICE VECTOR ORG = 000BH
;************************************************************************
;
    ORG    00BH
    CLR  TR0              ; TR0 = 0, STOP TIMER0
    MOV  TL0,R6
    MOV  TH0,R7
    RETI
;************************************************************************
;
;*  64K APROM MAIN PROGRAM
;************************************************************************
;
    ORG   100H

MAIN_64K:

    MOV A,P1                   ; SCAN P1.0
    ANL A,#01H
    CJNE A,#01H,PROGRAM_64K   ; IF P1.0 = 0, ENTER IN-SYSTEM PROGRAMMING MODE
    JMP NORMAL_MODE

PROGRAM_64K:
    MOV CHPENR,#87H      ; CHPENR = 87H, CHPCON REGISTER WRTE ENABLE
    MOV CHPENR,#59H      ; CHPENR = 59H, CHPCON REGISTER WRITE ENABLE
    MOV CHPCON,#03H      ; CHPCON = 03H, ENTER IN-SYSTEM PROGRAMMING MODE
    MOV TCON,#00H        ; TR = 0 TIMER0 STOP
    MOV IP,#00H          ; IP = 00H
    MOV IE,#82H          ; TIMER0 INTERRUPT ENABLE FOR WAKE-UP FROM IDLE MODE
```

```
        MOV R6,#FEH          ; TL0 = FEH
        MOV R7,#FFH          ; TH0 = FFH
        MOV TL0,R6
        MOV TH0,R7
        MOV TMOD,#01H        ; TMOD = 01H, SET TIMER0 A 16-BIT TIMER
        MOV TCON,#10H        ; TCON = 10H, TR0 = 1,GO
        MOV PCON,#01H        ; ENTER IDLE MODE FOR LAUNCHING THE IN-SYSTEM
                             ; PROGRAMMABILITY
;*******************************************************************************
;
;* Normal mode 64KB APROM program: depending user's application
;*******************************************************************************
;
NORMAL_MODE:

        .                    ; User's application program

        .

        .

        .
```

EXAMPLE 2:

```
;*************************************************************************************************************************
;
;* Example of 4KB LDROM program: This lorder program will erase the 64KB APROM first, then reads the new
;* code from external SRAM and program them into 64KB APROM bank. XTAL = 40 MHz
;*************************************************************************************************************************
;
     .chip 8052
     .RAMCHK OFF
     .symbols

     CHPCON   EQU   BFH
     CHPENR   EQU   F6H
     SFRAL    EQU   C4H
     SFRAH    EQU   C5H
     SFRFD    EQU   C6H
     SFRCN    EQU   C7H


        ORG   000H
        LJMP  100H           ; JUMP TO MAIN PROGRAM

 ;*********************************************************************
 ;
 ;* 1. TIMER0 SERVICE VECTOR ORG = 0BH
 ;*********************************************************************
 ;
     ORG 000BH
     CLR  TR0                ; TR0 = 0, STOP TIMER0
     MOV TL0,R6
     MOV TH0,R7
     RETI

;*********************************************************************
;
 ;*  4KB LDROM MAIN PROGRAM
 ;*********************************************************************
 ;
     ORG 100H
```

MAIN_4K:

```
        MOV CHPENR,#87H    ; CHPENR = 87H, CHPCON WRITE ENABLE.
        MOV CHPENR,#59H    ; CHPENR = 59H, CHPCON WRITE ENABLE.
        MOV A,CHPCON
        ANL A,#80H
        CJNE A,#80H,UPDATE_64K   ; CHECK  F04KBOOT MODE ?

        MOV CHPCON,#03H    ; CHPCON = 03H, ENABLE IN-SYSTEM PROGRAMMING.
        MOV CHPENR,#00H    ; DISABLE CHPCON WRITE ATTRIBUTE

        MOV TCON,#00H      ; TCON = 00H, TR = 0 TIMER0 STOP
        MOV TMOD,#01H      ; TMOD = 01H, SET TIMER0 A 16BIT TIMER
        MOV IP,#00H        ; IP = 00H
        MOV IE,#82H        ; IE = 82H, TIMER0 INTERRUPT ENABLED
        MOV R6,#FEH
        MOV R7,#FFH
        MOV TL0,R6
        MOV TH0,R7
        MOV TCON,#10H      ; TCON = 10H, TR0 = 1, GO
        MOV PCON,#01H      ; ENTER IDLE MODE
```

 UPDATE_64K:

```
        MOV CHPENR,#00H  ; DISABLE CHPCON WRITE-ATTRIBUTE
        MOV TCON,#00H    ; TCON = 00H , TR = 0 TIM0 STOP
        MOV IP,#00H      ; IP = 00H
        MOV IE,#82H      ; IE = 82H, TIMER0 INTERRUPT ENABLED
        MOV TMOD,#01H    ; TMOD = 01H, MODE1
        MOV R6,#3CH      ; SET WAKE-UP TIME FOR ERASE OPERATION, ABOUT 15 mS. DEPENDING
                         ; ON USER'S SYSTEM CLOCK RATE.
        MOV R7,#B0H
        MOV TL0,R6
        MOV TH0,R7
```

ERASE_P_4K:

```
        MOV SFRCN,#22H   ; SFRCN(C7H) = 22H  ERASE 64K
        MOV TCON,#10H    ; TCON = 10H, TR0 = 1,GO
        MOV PCON,#01H    ; ENTER IDLE MODE (FOR ERASE OPERATION)
```

```
;*********************************************************************
;
;* BLANK CHECK
;*********************************************************************
;
        MOV SFRCN,#0H    ; READ 64KB APROM MODE
        MOV SFRAH,#0H    ; START ADDRESS = 0H
        MOV SFRAL,#0H
        MOV R6,#FBH      ; SET TIMER FOR READ OPERATION, ABOUT 1.5 µS.
        MOV R7,#FFH
        MOV TL0,R6
        MOV TH0,R7
```

BLANK_CHECK_LOOP:

```
        SETB TR0         ; ENABLE TIMER 0
        MOV PCON,#01H    ; ENTER IDLE MODE
        MOV A,SFRFD      ; READ ONE BYTE
```

```
        CJNE A,#FFH,BLANK_CHECK_ERROR
        INC SFRAL              ; NEXT ADDRESS
        MOV A,SFRAL
        JNZ BLANK_CHECK_LOOP
        INC SFRAH
        MOV A,SFRAH
        CJNE A,#0H,BLANK_CHECK_LOOP   ; END ADDRESS = FFFFH
        JMP PROGRAM_64KROM


BLANK_CHECK_ERROR:

        MOV P1,#F0H
        MOV P3,#F0H
        JMP $


;********************************************************************************
;
;* RE-PROGRAMMING 64KB APROM BANK
;********************************************************************************
;
PROGRAM_64KROM:

        MOV DPTR,#0H       ; THE ADDRESS OF NEW ROM CODE
        MOV R2,#00H        ; TARGET LOW BYTE ADDRESS
        MOV R1,#00H        ; TARGET HIGH BYTE ADDRESS
        MOV DPTR,#0H       ; EXTERNAL SRAM BUFFER ADDRESS
        MOV SFRAH,R1       ; SFRAH, TARGET  HIGH ADDRESS
        MOV SFRCN,#21H     ; SFRCN(C7H) = 21 (PROGRAM 64K)
        MOV R6,#0CH        ; SET TIMER FOR PROGRAMMING, ABOUT 150 µS.
        MOV R7,#FEH
        MOV TL0,R6
        MOV TH0,R7


PROG_D_64K:

        MOV SFRAL,R2       ; SFRAL(C4H) = LOW BYTE ADDRESS
        MOVX A,@DPTR       ; READ DATA FROM EXTERNAL SRAM BUFFER
        MOV SFRFD,A        ; SFRFD(C6H) = DATA IN
        MOV TCON,#10H      ; TCON = 10H, TR0 = 1,GO
        MOV PCON,#01H      ; ENTER IDLE MODE (PRORGAMMING)
        INC DPTR
        INC R2
        CJNE R2,#0H,PROG_D_64K
        INC  R1
        MOV SFRAH,R1
        CJNE R1,#0H,PROG_D_64K


;********************************************************************************
;
; * VERIFY 64KB APROM BANK
;********************************************************************************
;
        MOV R4,#03H          ; ERROR COUNTER
        MOV R6,#FBH          ; SET TIMER FOR READ VERIFY, ABOUT 1.5 µS.
        MOV R7,#FFH
        MOV TL0,R6
        MOV TH0,R7
        MOV DPTR,#0H         ; The start address of sample code
        MOV R2,#0H           ; Target  low byte address
        MOV R1,#0H           ; Target  high byte address
```

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```
        MOV SFRAH,R1        ; SFRAH, Target high address
        MOV SFRCN,#00H      ; SFRCN = 00 (Read ROM CODE)

READ_VERIFY_64K:
        MOV SFRAL,R2        ; SFRAL(C4H) = LOW ADDRESS
        MOV TCON,#10H       ; TCON = 10H, TR0 = 1,GO
        MOV PCON,#01H
        INC R2
        MOVX A,@DPTR
        INC DPTR
        CJNE A,SFRFD,ERROR_64K
        CJNE R2,#0H,READ_VERIFY_64K
        INC R1
        MOV SFRAH,R1
        CJNE R1,#0H,READ_VERIFY_64K


;****************************************************************************
;
;* PROGRAMMING COMPLETLY, SOFTWARE RESET CPU
;****************************************************************************
;
        MOV CHPENR,#87H     ; CHPENR = 87H
        MOV CHPENR,#59H     ; CHPENR = 59H
        MOV CHPCON,#83H     ; CHPCON = 83H, SOFTWARE RESET.

ERROR_64K:
        DJNZ R4,UPDATE_64K  ; IF ERROR OCCURS, REPEAT 3 TIMES.
        .                   ; IN-SYSTEM PROGRAMMING FAIL, USER'S PROCESS TO DEAL WITH IT.
        .
        .
        .
```

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Note: All data and specifications are subject to change without notice.